ENGINEERING DEPT.		PRODUCT SPECIFICATION	SPEC.NO.:	SPCH053A
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#### 1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

### 2. APPLICABLE STANDARDS:

MIL - STD - 202 Methods for test of connectors for electronic equipment

MIL - STD - 1344 Test methods for electrical connectors

L-STD-020 Resistance to soldering Temperature for

J-STD-020 Resistance to soldering Temperature for through hole Mounted Devices SS-00254 Test methods for electronic components ,LEAD-FREE soldering Part design

standards

3. APPLICABLE SERIES NO.: CH91 Series

## 4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

#### 5. MATERIALS

See attached drawings

### 6. ACCOMMODATED P.C.BOARD

 $0.8 \text{ mm} (.031'') \sim 1.6 \text{ mm} (.063'')$ 



REVIEWED: <u>David</u> APPROVED: <u>Eisley</u> VERIFIED: <u>Clark</u>.



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# 7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	
7.1	Rated current and voltage		1A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. 100mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 1000 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than $1000~\text{M}\Omega$

# 8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Pin retention force	Push pin from insulator base at speed	More than 800 gram
		25 ±3 mm per minute	

# 9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30°C max.
9.2	Vibration	1.5 mm 10 - 55 - 10 HZ/minute each 2 hours for X,Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.3	Solderability	Lead-Free Process: Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5°C	Minimum: 95% of immersed area
9.4	Resistance to soldering heat	Lead-Free Wave Flow Process Soldering time: 5 ± 0.5 second Soldering pot: 260 ± 5°C	No damage
9.5	Heat aging	105± 2°C, 96 hours	No damage
9.6	Humidity	40±2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3



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	ITEM	TEST CONDITION	REQUIREMENT	
9.7	Temperature cycling	One cycle consists of: $(1) -55 ^{+0}_{-3}$ °C, 30 min. (2)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial	
		(3) 85 +3 °C, 30 min. (4)Room temp. 10-15 min. Total cycle: 5 cycle	Dielectric strength: To pass para 7-3	
9.8	Salt spray	Temperature: 35± 3°C Solution: 5± 1% Spray time: 48± 4 hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3	

10. AMBIENT TEMPERATURE RANGE: -40 to + 105°C